

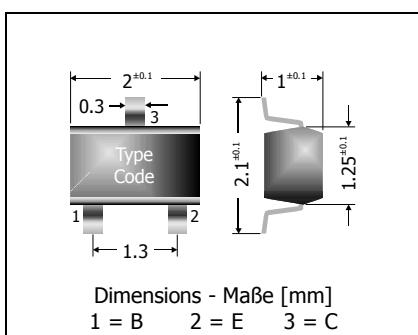
BC846W ... BC849W

NPN

Surface Mount General Purpose Si-Epi-Planar Transistors
Si-Epi-Planar Universaltransistoren für die Oberflächenmontage

NPN

Version 2011-07-07



Power dissipation – Verlustleistung

200 mW

Plastic case

SOT-323

Kunststoffgehäuse

Weight approx. – Gewicht ca.

0.01 g

Plastic material has UL classification 94V-0
Gehäusematerial UL94V-0 klassifiziertStandard packaging taped and reeled
Standard Lieferform gegurtet auf Rolle**Maximum ratings ($T_A = 25^\circ\text{C}$)****Grenzwerte ($T_A = 25^\circ\text{C}$)**

		BC846W	BC847W	BC848W BC849W
Collector-Emitter-volt. – Kollektor-Emitter-Spannung	B open	V_{CEO}	65 V	45 V
Collector-Base-voltage – Kollektor-Basis-Spannung	E open	V_{CBO}	80 V	50 V
Emitter-Base-voltage – Emitter-Basis-Spannung	C open	V_{EBO}	6 V	5 V
Power dissipation – Verlustleistung		P_{tot}	200 mW ¹⁾	
Collector current – Kollektorstrom (dc)		I_C	100 mA	
Peak Collector current – Kollektor-Spitzenstrom		I_{CM}	200 mA	
Peak Base current – Basis-Spitzenstrom		I_{BM}	200 mA	
Peak Emitter current – Emitter-Spitzenstrom		- I_{EM}	200 mA	
Junction temperature – Sperrsichttemperatur		T_j	-55...+150°C	
Storage temperature – Lagerungstemperatur		T_s	-55...+150°C	

Characteristics ($T_j = 25^\circ\text{C}$)**Kennwerte ($T_j = 25^\circ\text{C}$)**

		Min.	Typ.	Max.
DC current gain – Kollektor-Basis-Stromverhältnis				
$V_{CE} = 5 \text{ V}, I_C = 10 \mu\text{A}$	Group A	h_{FE}	–	90
	Group B	h_{FE}	–	150
	Group C	h_{FE}	–	270
$V_{CE} = 5 \text{ V}, I_C = 2 \text{ mA}$	Group A	h_{FE}	110	180
	Group B	h_{FE}	200	290
	Group C	h_{FE}	420	520
Collector-Emitter saturation voltage – Kollektor-Sättigungsspannung ²⁾				
$I_C = 10 \text{ mA}, I_B = 0.5 \text{ mA}$		V_{CEsat}	–	90 mV
$I_C = 100 \text{ mA}, I_B = 5 \text{ mA}$		V_{CEsat}	–	250 mV
				600 mV

1 Mounted on P.C. board with 3 mm^2 copper pad at each terminal
 Montage auf Leiterplatte mit 3 mm^2 Kupferbelag (Lötpad) an jedem Anschluss

2 Tested with pulses $t_p = 300 \mu\text{s}$, duty cycle $\leq 2\%$ – Gemessen mit Impulsen $t_p = 300 \mu\text{s}$, Schaltverhältnis $\leq 2\%$

Characteristics ($T_j = 25^\circ\text{C}$)Kennwerte ($T_j = 25^\circ\text{C}$)

		Min.	Typ.	Max.
Base-Emitter saturation voltage – Basis-Sättigungsspannung ²⁾ $I_C = 10 \text{ mA}, I_B = 0.5 \text{ mA}$ $I_C = 100 \text{ mA}, I_B = 5 \text{ mA}$	V_{BEsat} V_{BEsat}	– –	700 mV 900 mV	– –
Base-Emitter-voltage – Basis-Emitter-Spannung ²⁾ $V_{CE} = 5 \text{ V}, I_C = 2 \text{ mA}$ $V_{CE} = 5 \text{ V}, I_C = 10 \text{ mA}$	V_{BE} V_{BE}	580 mV –	660 mV –	700 mV 720 mV
Collector-Base cutoff current – Kollektor-Basis-Reststrom $V_{CB} = 30 \text{ V}, (\text{E open})$ $V_{CE} = 30 \text{ V}, T_j = 125^\circ\text{C}, (\text{E open})$	I_{CBO} I_{CBO}	– –	– –	15 nA 5 μA
Emitter-Base cutoff current $V_{EB} = 5 \text{ V}, (\text{C open})$	I_{EBO}	–	–	100 nA
Gain-Bandwidth Product – Transitfrequenz $V_{CE} = 5 \text{ V}, I_C = 10 \text{ mA}, f = 100 \text{ MHz}$	f_T	100 MHz	–	–
Collector-Base Capacitance – Kollektor-Basis-Kapazität $V_{CB} = 10 \text{ V}, I_E = i_e = 0, f = 1 \text{ MHz}$	C_{CBO}	–	3.5 pF	6 pF
Emitter-Base Capacitance – Emitter-Basis-Kapazität $V_{EB} = 0.5 \text{ V}, I_C = i_c = 0, f = 1 \text{ MHz}$	C_{EBO}	–	9 pF	–
Noise figure – Rauschzahl $V_{CE} = 5 \text{ V}, I_C = 200 \mu\text{A}, R_G = 2 \text{ k}\Omega$ $f = 1 \text{ kHz}, \Delta f = 200 \text{ Hz}$	F F	– –	2 dB 1.2 dB	10 dB 4 dB
Thermal resistance junction to ambient air Wärmewiderstand Sperrsicht – umgebende Luft	R_{thA}	< 620 K/W ¹⁾		
Recommended complementary PNP transistors Empfohlene komplementäre PNP-Transistoren	BC856W ... BC859W			
Marking of available current gain groups per type Stempelung der lieferbare Stromverstärkungsgruppen pro Typ	BC846AW = 1A BC847AW = 1E BC848AW = 1J	BC846BW = 1B BC847BW = 1F BC848BW = 1K	BC847CW = 1G BC848CW = 1L BC849BW = 2B	BC849CW = 2C

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